

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (previously presented): The spin coating apparatus according to claim 2,
wherein the extended projection part of the spin chuck surrounds a circumference of the
wafer while being in contact with the circumference of the wafer mounted on the mount part.

2. (currently amended): A spin coating apparatus for coating photoresist, comprising:
a wafer;
a spin chuck comprising a mount part, for mounting the a wafer thereon, and an extended
projection part for facilitating formation of an edge-bead thereon; and
a nozzle for depositing photoresist onto a wafer mounted on the mount part of the spin
chuck;
wherein the extended projection part of the spin chuck has a height lower than that of the
wafer mounted on the mount part.

3. - 5. (canceled).

6. (previously presented): The spin coating apparatus according to claim 2, which further
comprises a gas exhaust part disposed so that gas is exhausted from an edge of the wafer in a
turning direction of the wafer and a centrifugal direction upon rotation of the wafer.

7. (currently amended): A spin coating apparatus for coating photoresist, comprising:

a wafer;

a spin chuck for rotating ~~a~~the wafer;

a nozzle part for depositing photoresist onto the wafer mounted on the spin chuck; and

a gas exhaust part disposed so that gas is exhausted from an edge of the wafer in a turning direction of the wafer and a centrifugal direction upon rotation of the wafer;

wherein the spin chuck comprises a mount part and an extended projection part, the extended projection part surrounding a circumference of the wafer while being in contact with the circumference of the wafer mounted on the mount part;

wherein the extended projection part of the spin chuck has a height lower than that of the wafer mounted on the mount part.

8. (canceled).

9. (previously presented): The spin coating apparatus according to claim 2, wherein the extended projection part of the spin chuck is physically attached to the mount part of the spin chuck.

10. (previously presented): The spin coating apparatus according to claim 2, wherein the entire circumference edge of the wafer is in contact with the extended projection part of the spin chuck.

11. (currently amended): ~~The~~A spin coating apparatus according to claim 2, for coating photoresist, comprising:

a spin chuck comprising a mount part, for mounting a wafer thereon, and an extended projection part for facilitating formation of an edge bead thereon; and

a nozzle for depositing photoresist onto a wafer mounted on the mount part of the spin chuck;

wherein the spin chuck further comprises a separation part for separating the wafer from the spin chuck; and

wherein the separation part comprises removable plugs that are inserted through corresponding holes in the spin chuck to push against the bottom of the wafer and separate the wafer from the spin chuck.

12. (previously presented): The spin coating apparatus according to claim 6, wherein the gas exhaust part is disposed above the wafer, and the gas is exhausted to remove an edge-bead.

13. (previously presented): The spin coating apparatus according to claim 7, wherein the gas exhaust part is disposed above the wafer, and the gas is exhausted to remove an edge-bead.